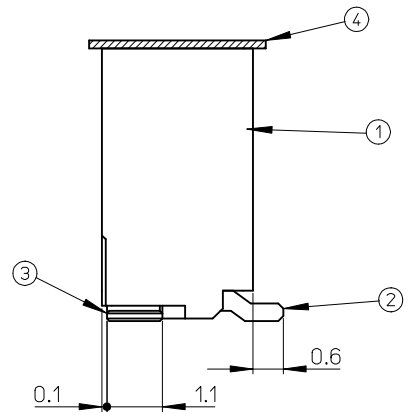
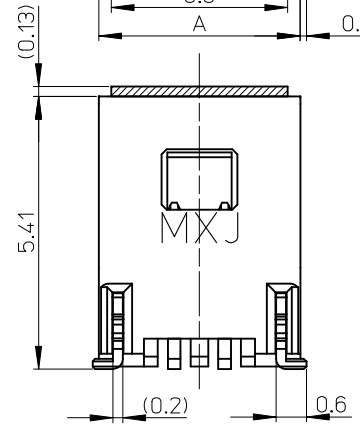


参考パターンレイアウト
 RECOMMENDED PATTERN DIM. (REF)
 SCALE: 5-1 (メタルマスク厚: 0.12mm)



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	ポリアミド UL94V-0 色: 自然色 POLYAMIDE, UL94V-0, COLOR: NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 部分金メッキ: 0.1 μm MIN. SEPARATED GOLD PLATING ニッケルメッキ(下地): 1.0 μm MIN. NICKEL (UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0 μm MIN. TIN ニッケルメッキ(下地): 1.0 μm MIN. NICKEL (UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

1. 嵌合相手: 501330-****
MATE WITH: 501330-****
2. ソルダーピン及びネイル平坦度は、0.1 MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1 MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 6~15極については、SD-504449-002を参照下さい。
REFER TO SD-504449-002 ABOUT 6-15CKT.
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

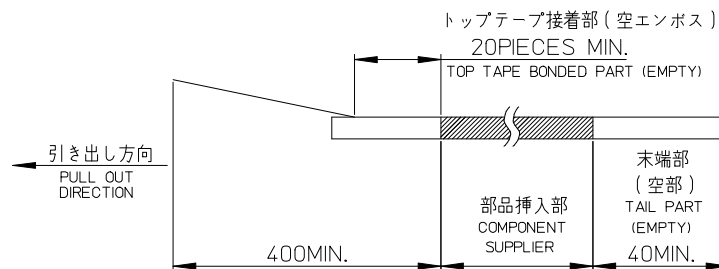
4.0	7.0	504449-0507	5
3.0	6.0	504449-0407	4
2.0	5.0	504449-0307	3
1.0	4.0	504449-0207	2
B	A	EMBOSSED PACKAGE	CKT.
		オーダー番号 ORDER NO.	

※対応可能な極数は、別途お問い合わせ下さい。

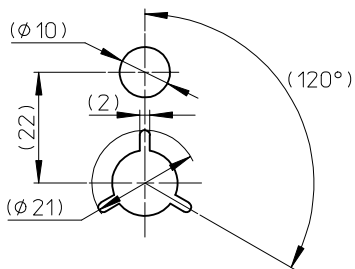
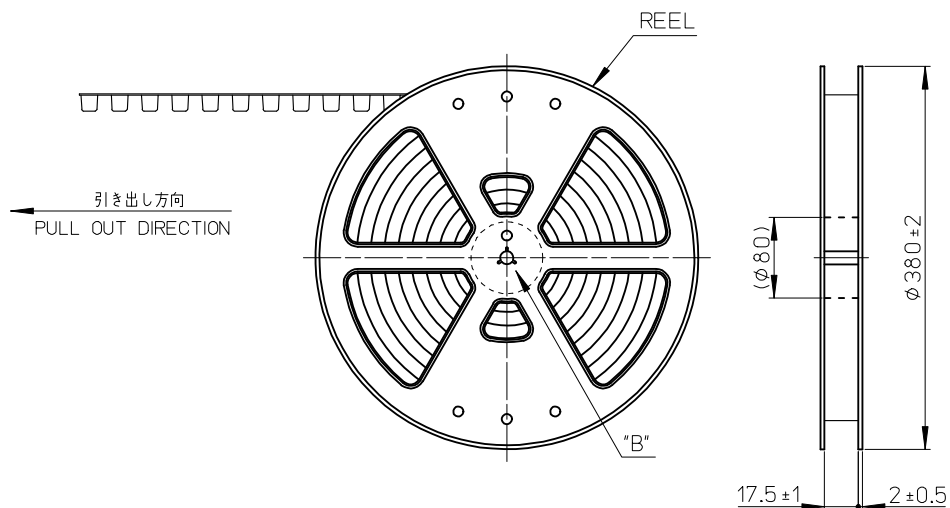
RELEASED EC NO: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21 REV O	DESCRIPTION 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		CONNECTOR SERIES NO. 504449-***09	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 2-5CKT				
		DRAWN BY KWASHIO	DATE 2012/12/13	MATERIAL NO. SEE TABLE			
		CHECKED BY	DATE	DOCUMENT NO. SD-504449-001			
		APPROVED BY YOITO	DATE 2012/12/21	SHEET NO. 1 OF 1			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量：1100個/リール
NUMBER OF CONNECTORS : 1100PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



4. 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE : POLYPROPYLENE
トップテープ：PET、PE、REF
TOP TAPE
リール：ポリスチレン<リサイクル材を含む>
REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(504449-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 504449-0607~1507)



DETAIL "B"

RELEASED EC NO: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER ±0.2		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 OVER 30 UNDER ±0.25						DRAWN BY KWASHIO	DATE 2012/12/13
		30 OVER ±0.3		CHECKED BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG			
		ANGULAR ±1 °		APPROVED BY YOITO	DATE 2012/12/21	molex			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-504449-003		SHEET NO. 1 OF 2	

EMBOSSSED TAPE

1.6幅テープ
16 WIDTH TAPE

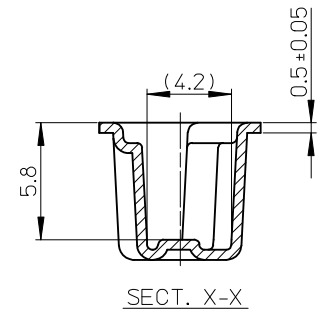
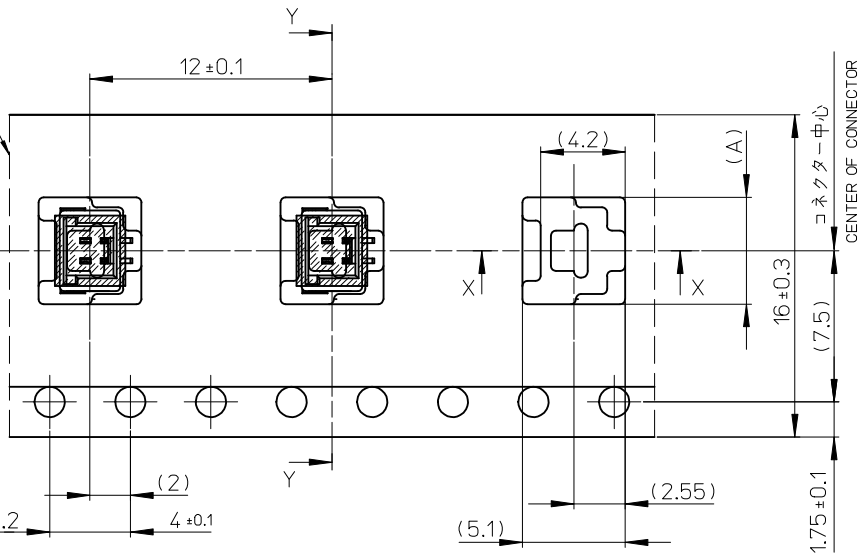
CONNECTOR

TOP TAPE

SECT. Y-Y

累積ピッチ: 40 ± 0.2
ACUUMLATIVE PITCH

引き出し方向
PULL OUT DIRECTION



8.3	504449-0507	5
7.3	504449-0407	4
6.3	504449-0307	3
5.3	504449-0207	2
(A)	EMBOSSSED PACKAGE	CKT.
	オーダー番号 ORDER NO.	

CONNECTOR SERIES NO. 504449-***9

SEE SHEET1 EC NO. J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ± 0.2 10 OVER 30 UNDER ± 0.25 30 OVER ± 0.3	DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
	ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY YOITO	DATE 2012/12/21	molex		
		APPROVED BY YOITO	DATE 2012/12/21	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-504449-003	SHEET NO. 2 OF 2
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			